



TECHNISCHE  
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# IAP-SEMINAR

## EINLADUNG

Termin: **Dienstag, 20.3.2012 um 16:00 Uhr**  
Ort: **Technische Universität Wien,  
Institut für Angewandte Physik,  
Seminarraum 134A, Turm B (gelbe Leitfarbe), 5. OG  
1040 Wien, Wiedner Hauptstraße 8-10**

Vortragender: **Prof. Mirko Černák**  
Department of Physical Electronics, Masaryk University  
Brno, Czech Republic

Thema: **Mechanism and applications of Diffuse Coplanar Surface  
Barrier Discharge**

### Kurzfassung

In a contrast to common plasma applications for surface modifications of high-added value materials for microelectronics, medicine, etc. a novel type of atmospheric plasma source based on the Diffuse Coplanar Surface Barrier Discharge (DCSBD) developed at Masaryk University, Brno and Comenius University, Bratislava makes possible low-cost in-line treatment of a wide scale of standard flat and web materials.

Advantageously in comparison to competitive plasma techniques this plasma source is capable of generating visually uniform “cold” high-power-density diffuse plasmas in any working gas, including ambient air and atmospheric-pressure oxygen, without the use of He or Ar. Very high plasma power densities achieved ( $\sim 100 \text{ W/cm}^3$ ) allows for short plasma exposure times on the order of 0.1 s and, consequently, high treatment speeds.

In the talk the basic physical mechanism of DCSBD and results on in-line air-plasma polypropylene fabrics activation, inorganic nanofibers calcination, glass, ITO and Al surface cleaning, and other applications will be discussed.

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*Alle interessierten Kolleginnen und Kollegen sind zu diesem Seminar  
(45 min mit anschließender gemeinsamer Diskussion) herzlich eingeladen.*

*H. Störi e.h.  
(LVA-Leiter)*